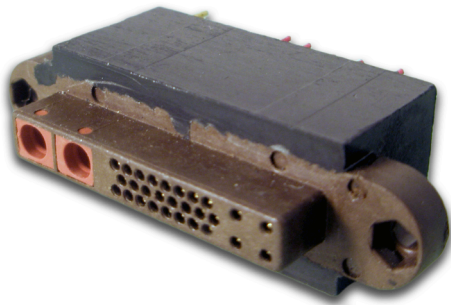


APPLICATION NOTE

www.ittcannon.com**Mixed Signal HV MDM Interconnect****October 2008**

The Challenge

Initially developed by ITT-ICS for high density packaging in harsh environments, the MDM micro series of connectors have been successfully used in many Aerospace applications. Aerospace Customers challenged ITT to develop a high density mixed signal connector capable of carrying high voltage signals along with low voltage signals within the same package. In addition, the new interconnect had to be able to prevent arcing between contacts.



MDM High Temperature Interconnect Assembly

Product Features

- Complete turnkey interconnect configuration
- MDM connector with HV contacts
- 2000 VDC
- Twist Pin Contact system for LV signals
- Crimped gold plated contacts
- Combination of 0.050 & 0.100 spacing
- Integrated silicone towers
- Straight board mount receptacle

Applications

- Avionics systems
- Commercial Aircraft Systems
- Launch Vehicle systems
- Radar Systems

The ITT Solution ...

ITT Interconnect Solutions Cannon designed the high voltage MDM series by designing an integrated high voltage contact system with isolation towers and a silicone sealing method to accommodate multiple voltage outputs. The turnkey solution allows for the utilization of advanced materials which prevent electrical arching at high altitude conditions.

For application assistance, please contact:

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